

PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10044141	FILING DATE 01/11/2002	CLASS 257	SUBCLASS 723	GAU 2811	EXAMINER <i>Chw</i>
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\*\*APPLICANTS: Paek Jong Sik, *Chw*

\*\*CONTINUING DATA VERIFIED:

\*\* FOREIGN APPLICATIONS VERIFIED:  
REPUBLIC OF KOREA 2001-02160 01/15/2001

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PG-PUB ☐ DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no  
35 USC 119 conditions met ☐ yes ☐ no  
Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

AMKOR-018A

TITLE : Semiconductor package with stacked dies

U.S. DEPT. OF COM. PAT. & TM. FTD-4315 (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
ISSUE FEE		Total Claims	Print Claim for O.G.
Amount Due	Date Paid	DRAWING	
<input type="checkbox"/> TERMINAL DISCLAIMER		Sheets Drawg.	Figs. Drawg.
		Print Fig.	
PREPARED FOR ISSUE		Application Examiner	
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